CURRICULUM: 120 ECTS (30 ECTS per Semester)

1st Semester	LV-Typ	SWS	ECTS
Analog Circuit Design	ILV	3	5
Digital Circuit Design	ILV	3	5
Electronic Packaging	ILV	2	3
Design Tools and Laboratory Engineering	ILV	3	3
Software Design and Architectures	ILV	3	5
Data Analysis	ILV	3	5
System Requirements Engineering	ILV	2	3
Intercultural Communication	SE	1	1
		20	**30**

2nd Semester	LV-Typ	SWS	ECTS
Radio Frequency Engineering	ILV	4	7
Machine Learning and Optimization	ILV	3	6
Embedded Systems Engineering			
Computer Architectures and Programming	ILV	4	6
Digital Signal Processing	ILV	3	5
Software Quality and Security	ILV	4	6
		18	**30**

3rd Semester	LV-Typ	SWS	ECTS
Project Management	SE	2	3
Electronic Engineering Project	PT	0,5	6
Embedded Systems Engineering			
System-on-Chip Design	ILV	4	6
Design Verification	ILV	2	3
Continuous Delivery in Embedded Systems	ILV	4	6
Realtime Computing	ILV	4	6
		16,5	**30**

4th Semester	LV-Typ	SWS	ECTS
Innovation Management	SE	2	2
Presentations and Meetings	SE	1	1
Scientific Working	SE	1	2
Master's Thesis	MA	0,5	22
Master's Exam	FA	0	3
		4,5	**30**

ILV = Integrated course, PT = Project, MA = Master's Thesis,
FA = Master's Exam, SE = Seminar, SWS = Hours per week,
ECTS = European Credit Transfer and Accumulation System